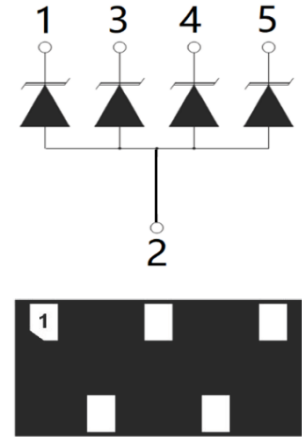


Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to
IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
IEC 61000-4-4 (EFT) 40A(5/50ns)
- ◆ Working voltages: 5V
- ◆ Protects five I/O lines
- ◆ Ultra Low capacitance: 0.3pf (typical between I/O channel)
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



DFN2010-5

Applications

- ◆ High Definition Multi-Media Interface (HDMI)
- ◆ USB 1.1/2.0/3.0/OTG
- ◆ IEEE 1394 Firewire Ports
- ◆ Projection TV Monitors and Flat Panel Displays
- ◆ Notebook Computers
- ◆ Set Top Box

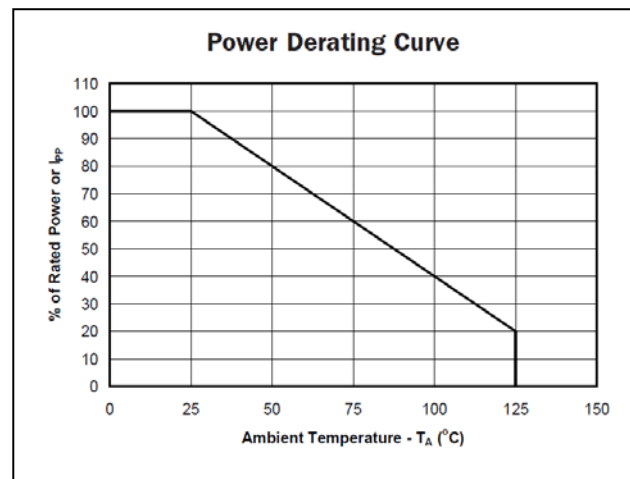
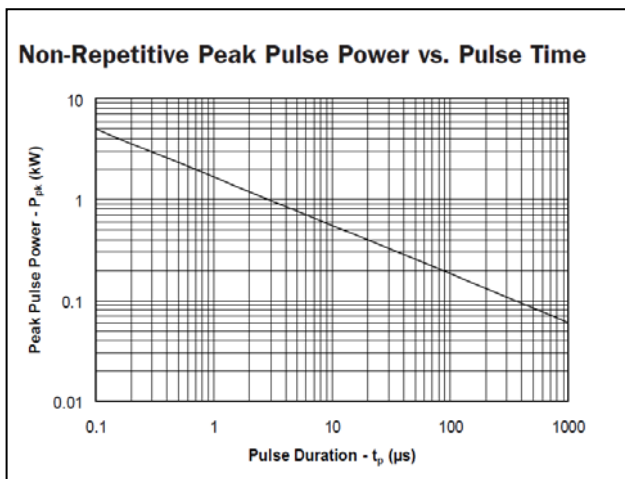
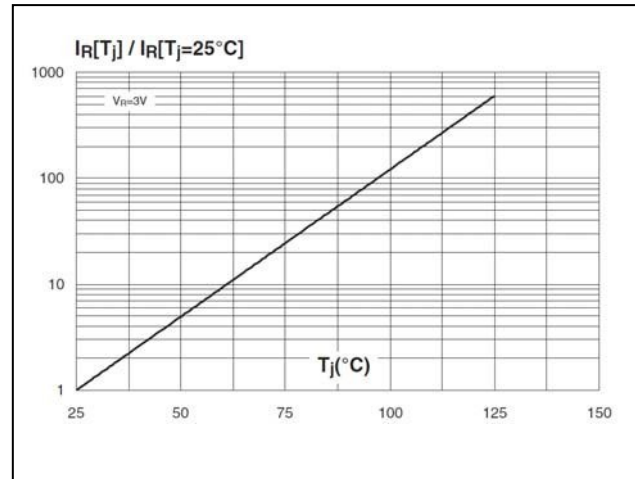
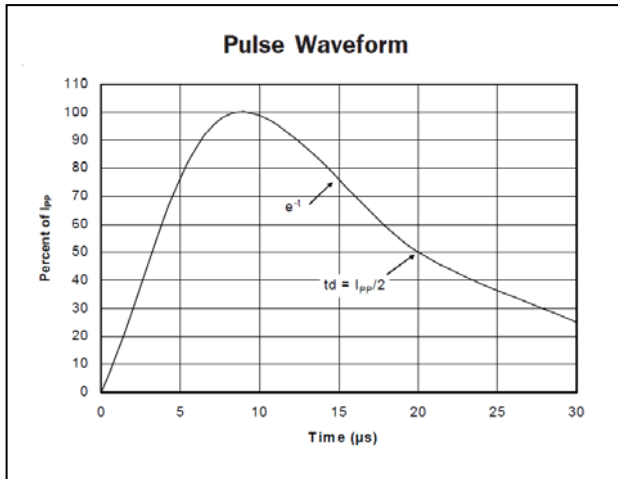
Maximum Rating @ $T_a = 25^\circ C$ unless otherwise specified

Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	150	Watts
T_L	Lead Soldering Temperature	260(10sec.)	$^\circ C$
T_J	Operating Temperature	-55 to +125	$^\circ C$
T_{STG}	Storage Temperature	-55 to +150	$^\circ C$

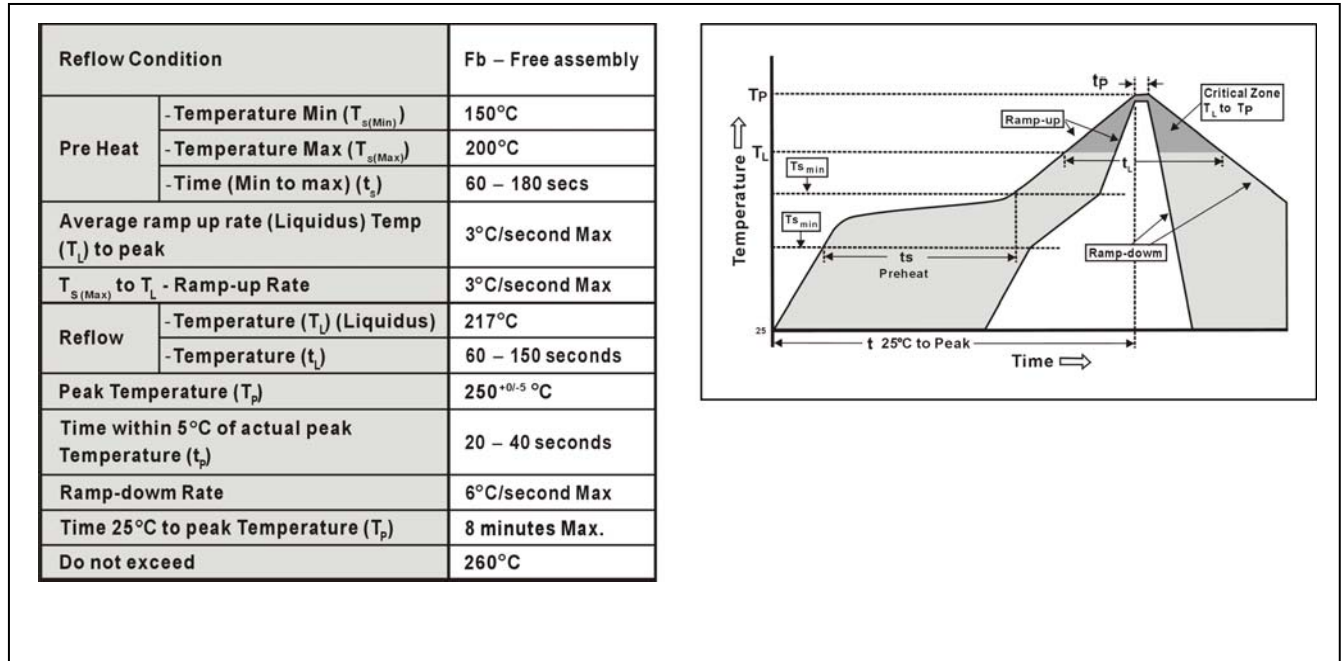
Electrical Characteristics@ Ta=25℃ unless otherwise

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{RWM}	Reverse Working Voltage	Any I/O to Ground			5.0	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA, Any I/O to Ground	6.0			V
I _R	Reverse Leakage Current	V _{RWM} = 5V, Any I/O to Ground			1	μA
V _F	Diode Forward Voltage	I _F = 15mA		0.85	1.2	V
V _C	Clamping Voltage	I _{PP} = 1A, t _p = 8/20μs, any I/O pin to Ground			15.5	V
		I _{PP} = 3A, t _p = 8/20μs, any I/O pin to Ground			25	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz, between I/O pins		0.35	0.45	pF
		V _R = 0V, f = 1MHz, any I/O pin to Ground		0.6	0.8	pF

Typical Characteristics@ Ta=25°C unless otherwise specified



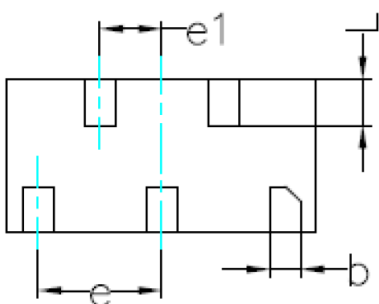
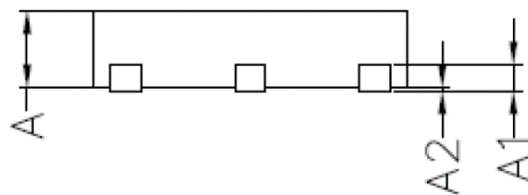
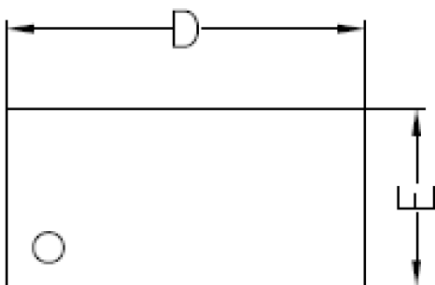
Soldering Parameters



Package Outline

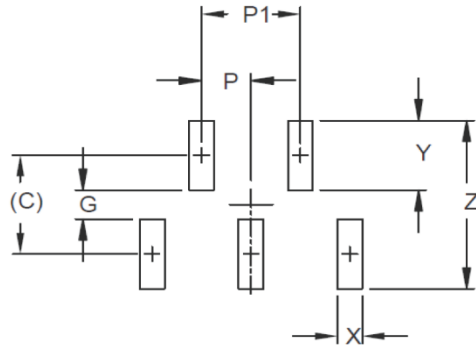
Plastic surface mounted package

DFN2010-5



Package Dimension			
	Min	Nom	Max
D	1.55	2.00	1.65
E	0.95	1.00	1.05
L	0.25	0.30	0.35
b	0.15	0.20	0.25
e1	0.40BSC		
e	0.80BSC		
A	0.45	0.50	0.55
A1	0.15REF		
A2	0.00	0.02	0.05

Soldering Footprint



DIMENSIONS	
DIM	MILLIMETERS
C	(0.85)
G	0.25
P	0.40
P1	0.80
X	0.20
Y	0.60
Z	1.45

Package And Marking Information

Device	Package	Shipping	Reel Size
ZX0534P	DFN2010-5	3000/Reel	7 inch